Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F-0403-08** DATE: 3/17/04
Product Affected: IDT7207, IDT7208

Date Effective: 6/17/04

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ■ Date Code "Y" Prefix
- ☐ Other

Contact: Dasharath Patel
Title: Quality Assurance Manager
Phone #: (408) 330-1488
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E-mail: Dasharath.Patel@idt.com

Attachment:: ■ Yes ☐ No

Samples: Refer to page 2

DESCRIPTION AND PURPOSE OF CHANGE:
- ■ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ■ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

As a part of IDT's consolidation of wafer fab manufacturing operations, the devices listed above are transferred from FAB 2 (Salinas, CA) to FAB 4 (Hillsboro, OR). The process technology has been upgraded from CeMOS 7 to CeMOS 8. There is no change to data sheet specifications.

RELIABILITY/QUALIFICATION SUMMARY:

Device qualification is in progress and will verify that there is no change to the device reliability.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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PCN Summary

PCN Type: Process Technology Upgrade and Wafer Fabrication Site Change

Commodity: FIFO

Forecast or Execute: Execute

Planned or Unplanned: Planned

Data Sheet Change: None

Detail of Change: Starting 5/18/2004, customers will receive material manufactured either at FAB 2 or FAB 4. Please see below for means of distinguishing inventory.

FAB 2 material mark	Z-Step	Date Code:	Zyyww
FAB 4 material mark	Y-Step	Date Code:	Yyyww
		yy: Year	ww: Work Week

Die Revision (stepping)	Z	Y
Wafer Fab	Fab 2	Fab 4
Fab Technology	CeMOS7	CeMOS8
# Poly Layers	2	2
# Metal Layers	1	1
Minimum Gate Length	0.64 µ	0.6 µ
Die Dimensions (sq. mils)	IDT7207: 63.4K IDT7208: 101.5K	IDT7207: 63.4K IDT7208: 101.5K

Note: All speed grades and package types are affected. Please refer to the ordering information given in the datasheet for specific part number.

Sample Availability: Beginning 05/18/04

Production Shipments Customer shipments for this die revision will start 05/18/2004 unless specifically requested.

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Product Details

IDT Part Number	IDT Part Number	IDT Part Number
IDT7207L15D	IDT7207L25PI	IDT7208L20J
IDT7207L15J	IDT7207L30DB	IDT7208L20J8
IDT7207L15J8	IDT7207L30LB	IDT7208L20P
IDT7207L15P	IDT7207L30LB8	IDT7208L25J
IDT7207L20D	IDT7207L35D	IDT7208L25J8
IDT7207L20DB	IDT7207L35J	IDT7208L25JI
IDT7207L20J	IDT7207L35J8	IDT7208L25JI8
IDT7207L20J8	IDT7207L35P	IDT7208L25P
IDT7207L20LB	IDT7207L50D	IDT7208L25PI
IDT7207L20LB8	IDT7207L50DB	IDT7208L35J
IDT7207L20P	IDT7207L50J	IDT7208L35J8
IDT7207L25D	IDT7207L50J8	IDT7208L35P
IDT7207L25J	IDT7207L50LB	
IDT7207L25J8	IDT7207L50LB8	
IDT7207L25JI	IDT7207L50P	
IDT7207L25JI8	IDT7207L25LB	
IDT7207L25P	IDT7207L20DB/6351	

Qualification Plans: QFI-03-15, QFI-03-16

Test Vehicle: IDT7207Y, IDT7208Y

Test Description/Condition	Test Methods	IDT7207Y Required SS / # Fails	IDT7208Y Required SS / # Fails	Expected Completion
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45 / 0	45 / 0	5/1/04
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116 / 0	116 / 0	5/1/04
Latch-Up Immunity (+ - I and V stress, + - 100mA Trigger)	EIA/JESD 78	10 / 0	10 / 0	5/1/04
ESD Human Body Model	MIL-STD-883, Method 3015	3 / 0	3 / 0	5/1/04
ESD Charge Device Model	JESD22-C101	3 / 0	3 / 0	5/1/04